

## Fairchild Semiconductor Product Package Material Disclosure

Package Type	WL-CSP (1.0x1.5)						
Weight of Package (grams)	1.72E-03						
	Material	Wt in grams	Substance or Material	Wt% in component	Wt% in Finished Product	CAS #	Parts per Million
<b>Under Bump Metal</b>	Metal	4.50E-05	Nickel	98.00	2.62	7440-02-0	26193
			Gold	2.00	2.57 0.05	7440-57-5	25669 524
<b>Bump</b>	Solder	6.36E-04	Tin	95.50	37.02	7440-31-5	370198
			Silver	3.50	35.35	7440-22-4	353539
			Copper	1.00	1.30 0.37	7440-50-8	12957 3702
<b>Chip</b>	Silicon	1.04E-03	Silicon and trace metals	98.55	60.36	7440-21-3	603609
			Aluminum	1.45	59.49 0.54		594857 5368



### Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.